



PATENT

(5298-03500/PM99021)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

§ §

In re Application of:

Lau

Serial No. 09/476,669

Filed: December 30, 1999

For: METHOD FOR FORMING A

LIZATION STRUCTURE IN PEGRATED CIRCUIT

BC 12/14/0L

Group Art Unit: 1745 Examiner: Cantelmo, G.

Atty. Dkt. No. 5298-03500

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Box AF/Commissioner for Patents, Washington, D.C. 20231, por the gate indicated below: Patents, Washington, D.C. 20231, pp

December 2, 2002

in L. Daffer Date

AMENDMENT; RESPONSE AFTER FINAL REJECTION PURSUANT TO 37 CFR § 1.116

Box AF Commissioner for Patents Washington, D.C. 20231

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DEC 1 1 2002

TC 1700

Dear Sir/Madam:

This paper is submitted in response to the Office Action mailed August 30, 2002 to further highlight reasons why the application is in condition for allowance.

Please amend the case as follows.

IN THE SPECIFICATION

Please replace pg. 20, line 22 - pg. 21, line 7, with the amended paragraph below. A "marked-up" version of each amendment is included in Attachment A.

To resolve these problems, the present method is preferably configured to deposit metal atoms with sufficient force to sputter previously deposited metal away from the ion impact area. The impact energy of the metal ions on the microelectronic topography is largely determined by the